

PATENT ASSIGNMENT

Electronic Version v08
 Stylesheet Version v02

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT OF ASSIGNOR'S INTEREST |

CONVEYING PARTY DATA

| Name | Execution Date |
|------------------|----------------|
| WEN-HAN HUNG | 2006-07-18 |
| CHENG-TUNG HUANG | 2006-07-18 |
| KUN-HSIEN LEE | 2006-07-18 |
| SHYH-FANN TING | 2006-07-18 |
| LI-SHIAN JENG | 2006-07-18 |
| TZYY-MING CHENG | 2006-07-18 |
| CHIA-WEN LIANG | 2006-07-18 |
| NENG-KUO CHEN | 2006-07-18 |

RECEIVING PARTY DATA

| Name | Street Address | Internal Address | City | State/Country | Postal Code |
|-------------------------------|---|------------------|---------|---------------|-------------|
| UNITED MICROELECTRONICS CORP. | No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, | | Hsinchu | TAIWAN | |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|--------------------|----------|
| Application Number | 11459008 |

CORRESPONDENCE DATA

FAX NUMBER: 886223697233
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.

CUSTOMER NUMBER: 031561

| | |
|-------------------------|-------------|
| NAME OF PERSON SIGNING: | Belinda Lee |
| DATE SIGNED: | 2006-08-08 |

Total Attachments: 2

800026955

**PATENT
 REEL: 018216 FRAME: 0689**

OP \$40.00 11459008

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ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Wen-Han Hung

Date: July 18, 2006

Sole or First Joint Inventor: Wen-Han Hung

Signature: Cheng Tung Huang

Date: July 18, 2006

Second Joint Inventor (if any): Cheng-Tung Huang

Signature: Kun-Hsien Lee

Date: July 18, 2006

Third Joint Inventor (if any): Kun-Hsien Lee

Signature: Shyh-Fann Ting

Date: July 18, 2006

Fourth Joint Inventor (if any): Shyh-Fann Ting

Signature: Li-Shian Jeng

Date: July 18, 2006

Fifth Joint Inventor (if any): Li-Shian Jeng

Signature: Tzyy-Ming Cheng

Date: July 18, 2006

Sixth Joint Inventor (if any): Tzyy-Ming Cheng

Signature: Chia-Wen Liang

Date: July 18, 2006

Seventh Joint Inventor (if any): Chia-Wen Liang

Signature: Neng-Kuo Chen

Date: July 18, 2006

Eighth Joint Inventor (if any): Neng-Kuo Chen

ASSIGNMENT

WHEREAS,

- | | |
|-------------------|---------------------|
| 1. Wen-Han Hung | 2. Cheng-Tung Huang |
| 3. Kun-Hsien Lee | 4. Shyh-Fann Ting |
| 5. Li-Shian Jeng | 6. Tzyy-Ming Cheng |
| 7. Chia-Wen Liang | 8. Neng-Kuo Chen |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD FOR FORMING SEMICONDUCTOR DEVICE**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp.
of No. 3, Li-Hsin Rd.II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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